



M T B F (E I A J R C R - 9 1 0 2 B)

Model	G1-12
-------	-------

No.	Parts		Q'ty of Device	Failure rate [10 ⁻⁶ /H]	Reference
1	IC	Linear	2	0.0480	
2	Transistors	NPN/PNP	0	0.0000	
3	Transistors	Power NPN/PNP	1	0.0420	
4	FET	MOS FET	1	0.0990	
5	Diodes	FR	2	0.0440	
6	Diodes	Zener	1	0.0240	
7	Diodes	bridge	3	0.1980	
8	Resistors	Metal Film	17	0.2720	
9	Resistors	Power Film	3	0.1230	
10	Resistors	variable	1	0.0160	
11	Capacitors	Aluminum Electrolytic	6	0.1140	
12	Capacitors	Film	4	0.0336	
13	Transformer	Switching	1	0.0042	
14	Fuses		1	0.0200	
15	Connectors	Printed Crcuit Board	5	0.2600	
16	Connection	Hand Solder	8	0.0208	
17	Connection	Flow Solder	162	0.0842	
18	Connection	Crimp	18	0.0112	
19	Connection	Screw	4	0.0040	
20	Printed Crcuit Board	Through Hole	2	0.0900	
Total Failure Rate [10 ⁻⁶ /H]				1.5080	

M T B F	[H]	663,000
Ambient Temperature	[°C]	-
Load Factor	[%]	-